

IN THE SPECIFICATION:

At page 1, lines 6-10, change the paragraph to read as follows:

RELATED CASES

The present invention, as identified by the above title, is related to one other invention which is entitled "ELECTROMECHANICAL MODULE, FOR HOLDING IC-CHIPS IN A CHIP TESTING SYSTEM, THAT SYNCHRONIZES AND TRANSLATES TEST SIGNALS TO THE IC-CHIPS", having Serial Number 10/759,910. Both inventions are described herein with a single Detailed Description. Patent applications on both inventions were filed concurrently in the U.S. Patent Office on January 16, 2004.

On page 15, change the paragraph at lines 25-31, to read as follows:

A second advantage which is achieved with the chip holding module 20 of Fig. 2 results from each socket 28 having input terminals that are connected to the outputs of a respective set of signal translators 25. Due to that structure, a defective IC-chip 30 in any one socket 28 will not adversely effect the testing of another chip in any other socket.

On page 19, change the paragraph at lines 11-14, to read as follows:

R1

Component R1 is a resistor.
In the Fig. 5 embodiment,
the resistor R1 is fifty_
five ohms.